

MOSFETs Silicon N-channel MOS (U-MOSIV)

# **TK150F04K3L**

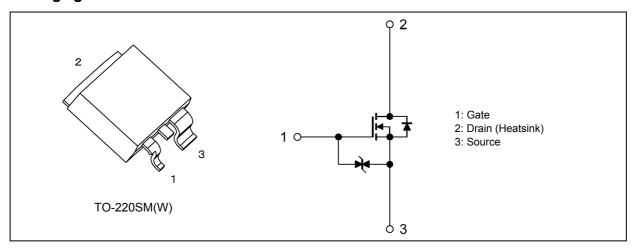
## 1. Applications

- · Switching Voltage Regulators
- · DC-DC Converters
- · Motor Drivers

#### 2. Features

- (1) Low drain-source on-resistance:  $R_{DS(ON)} = 1.7 \text{ m}\Omega$  (typ.) ( $V_{GS} = 10 \text{ V}$ )
- (2) Low leakage current:  $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 40 \text{ V)}$
- (3) Enhancement mode:  $V_{th} = 2.0$  to 3.0 V ( $V_{DS} = 10$  V,  $I_D = 1$  mA)

## 3. Packaging and Internal Circuit



# 4. Absolute Maximum Ratings (Note) (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics			Symbol	Rating	Unit
Drain-source voltage			V <sub>DSS</sub>	40	V
Gate-source voltage			$V_{GSS}$	±20	
Drain current (DC)		(Note 1)	I <sub>D</sub>	150	Α
Drain current (pulsed)		(Note 1)	I <sub>DP</sub>	450	
Power dissipation	(T <sub>c</sub> = 25°C)		$P_D$	300	W
Single-pulse avalanche energy		(Note 2)	E <sub>AS</sub>	238	mJ
Avalanche current			I <sub>AR</sub>	150	Α
Channel temperature		(Note 3)	T <sub>ch</sub>	175	Ç
Storage temperature		(Note 3)	T <sub>stg</sub>	-55 to 175	

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



## 5. Thermal Characteristics

Characteristics	Symbol	Max	Unit
Channel-to-case thermal resistance	R <sub>th(ch-c)</sub>	0.5	°C/W

Note 1: Ensure that the channel temperature does not exceed 175°C.

Note 2:  $V_{DD}$  = 25 V,  $T_{ch}$  = 25°C (initial), L = 11  $\mu$ H,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 150 A

Note 3: The definitions of the absolute maximum channel and storage temperatures are based on AEC-Q101.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.



### 6. Electrical Characteristics

## 6.1. Static Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cut-off current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	_	_	10	
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	40	_	_	٧
Drain-source breakdown voltage (Note 4)	V <sub>(BR)DSX</sub>	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	20	_	_	
Gate threshold voltage	$V_{th}$	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	3.0	
Drain-source on-resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = 6 V, I <sub>D</sub> = 75 A	_	2.1	3.2	mΩ
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 75 A	_	1.7	2.1	

Note 4: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

## 6.2. Dynamic Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Input capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	9400	_	pF
Reverse transfer capacitance	C <sub>rss</sub>		_	1200	_	
Output capacitance	C <sub>oss</sub>		_	1900		
Switching time (rise time)	t <sub>r</sub>	See Fig. 6.2.1	_	20	_	ns
Switching time (turn-on time)	t <sub>on</sub>		_	42	_	
Switching time (fall time)	t <sub>f</sub>		_	43	_	
Switching time (turn-off time)	t <sub>off</sub>		_	158		

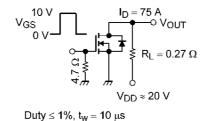


Fig. 6.2.1 Switching Time Test Circuit

## 6.3. Gate Charge Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Total gate charge (gate-source plus gate-drain)	Qg	$V_{DD} \approx 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 150 \text{ A}$		190		nC
Gate-source charge	$Q_{gs}$		_	127	_	
Gate-drain charge	$Q_{gd}$		_	63	_	

## 6.4. Source-Drain Characteristics (T<sub>a</sub> = 25°C unless otherwise specified)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Reverse drain current (DC)	(Note 5)	I <sub>DR</sub>	_	_	_	150	Α
Reverse drain current (pulsed)	(Note 5)	I <sub>DRP</sub>	_			450	
Diode forward voltage		V <sub>DSF</sub>	I <sub>DR</sub> = 150 A, V <sub>GS</sub> = 0 V	_	_	-1.2	V
Reverse recovery time		t <sub>rr</sub>	I <sub>DR</sub> = 150 A, V <sub>GS</sub> = 0 V	_	80	_	ns
Reverse recovery charge		Q <sub>rr</sub>	-dI <sub>DR</sub> /dt = 50 A/μs		80		nC

Note 5: Ensure that the channel temperature does not exceed 175°C.



# 7. Marking (Note)

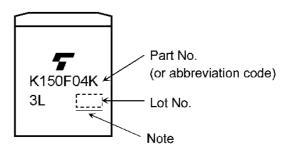


Fig. 7.1 Marking

Note: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product.

The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



#### 8. Moisture-Proof Packing

This device is packed in a moisture-proof laminated aluminum bag.

#### 8.1. Precautions for Transportation and Storage (Note)

- (1) Avoid excessive vibration during transportation.
- (2) Do not toss or drop the packed devices to avoid ripping of the bag.
- (3) After opening the moisture-proof bag, the devices should be assembled within two weeks in an environment of 5°C to 30°C and RH70% or below. Perform reflow at most twice.
- (4) The moisture-proof bag may be stored unopened for up to 24 months at 5°C to 30°C and RH90% or below.
- (5) If, upon opening the bag, the moisture indicator card shows humidity of 30% or above (the color of the 30% dot has changed from blue to pink) or the expiration date has passed, the devices should be baked as follows:

Baking conditions: 125°C for 48 hours.

Note: Since the tape materials are not heat-proof, devices should be placed on either heat-proof trays or aluminum magazines when baking.



The humidity indicator shows an approximate ambient humidity at 25°C. If the ambient humidity is below 30%, the color of all the indicator dots is blue. If, upon opening the bag, the color of the 30% dot has changed from blue to pink, the devices should be baked before assembly.

Fig. 8.1.1 Humidity Indicator

## 9. Characteristics Curves (Note)

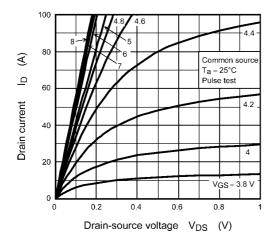


Fig. 9.1  $I_D - V_{DS}$ 

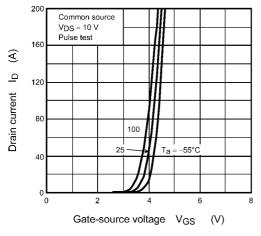


Fig. 9.3  $I_D - V_{GS}$ 

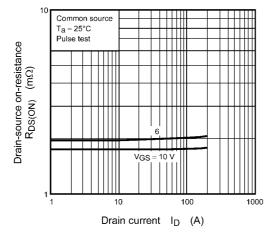


Fig. 9.5 R<sub>DS(ON)</sub> - I<sub>D</sub>

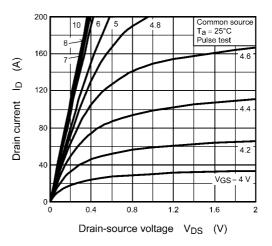


Fig. 9.2 I<sub>D</sub> - V<sub>DS</sub>

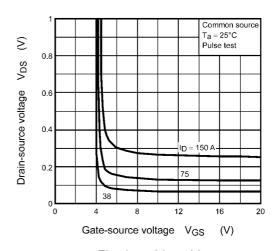


Fig. 9.4  $V_{DS} - V_{GS}$ 

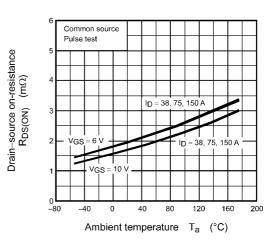


Fig. 9.6 R<sub>DS(ON)</sub> - T<sub>a</sub>

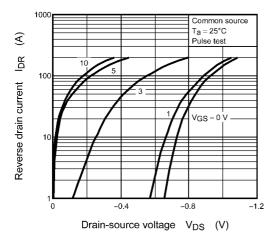


Fig. 9.7  $I_{DR}$  -  $V_{DS}$ 

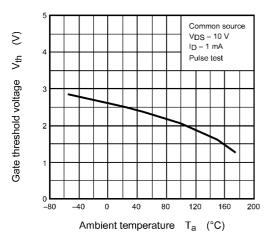


Fig. 9.9 Vth - Ta

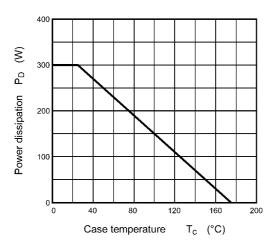


Fig. 9.11 P<sub>D</sub> - T<sub>c</sub> (Guaranteed Maximum)

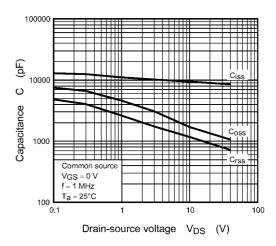


Fig. 9.8 Capacitance - V<sub>DS</sub>

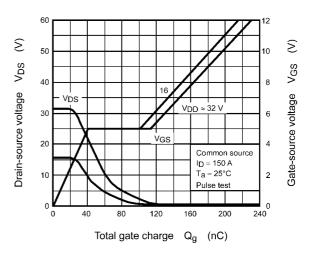


Fig. 9.10 Dynamic Input/Output Characteristics

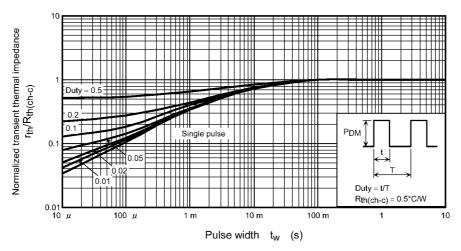


Fig. 9.12 r<sub>th</sub>/R<sub>th(ch-c)</sub> - t<sub>w</sub> (Guaranteed Maximum)

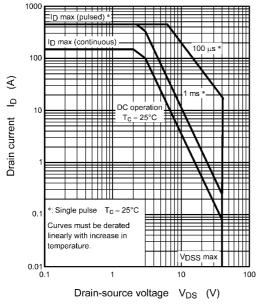


Fig. 9.13 Safe Operating Area (Guaranteed Maximum)

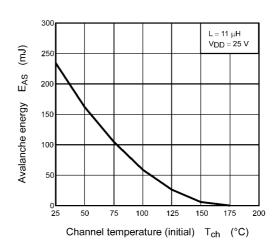


Fig. 9.14 E<sub>AS</sub> - T<sub>ch</sub> (Guaranteed Maximum)

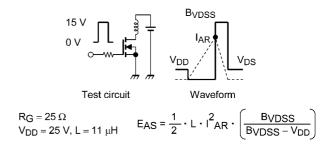


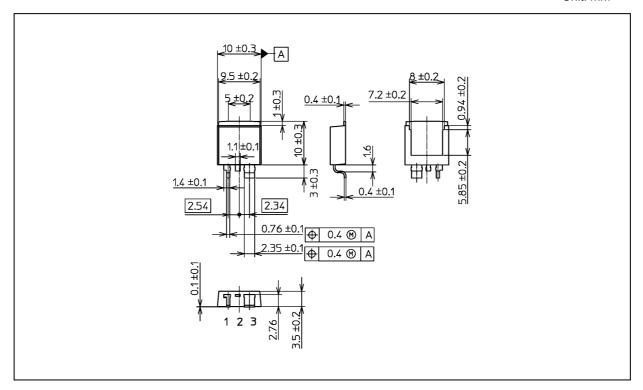
Fig. 9.15 Test Circuit/Waveform

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 1.07 g (typ.)

Package Name(s)	
TOSHIBA: 2-10W1S	
Nickname: TO-220SM(W)	

Rev.1.0



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